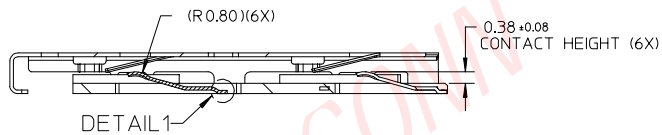
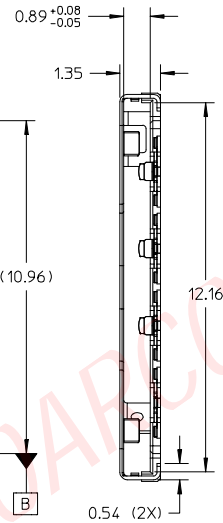
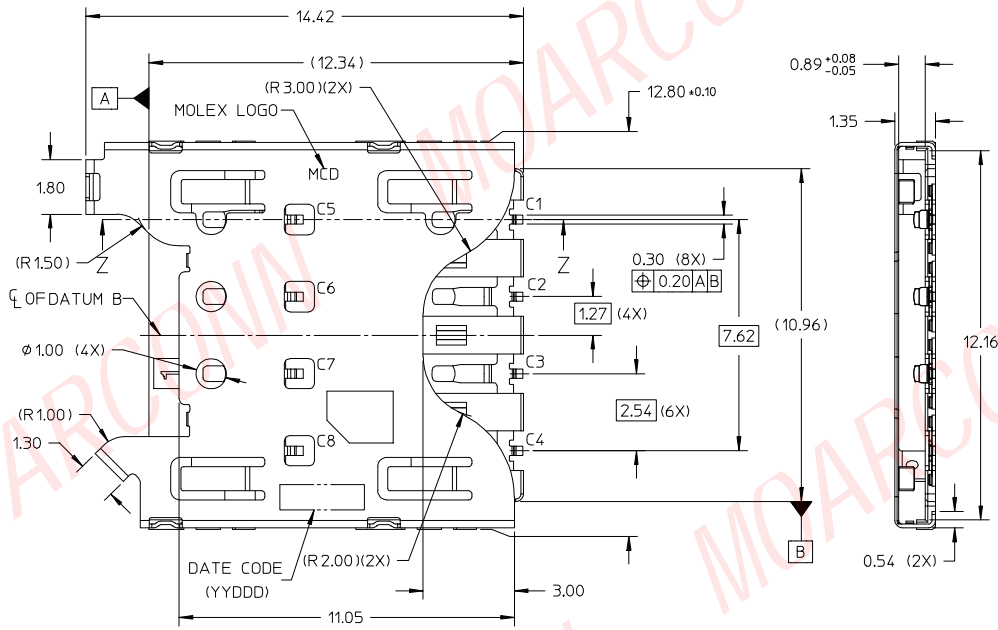
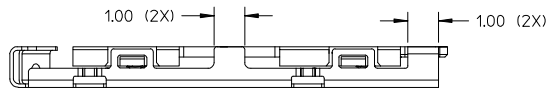
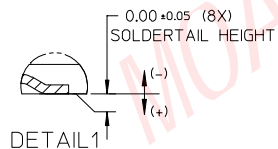


All materials, plating and process meet HF requirements.



SECTION Z-Z

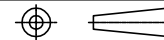


NOTE:

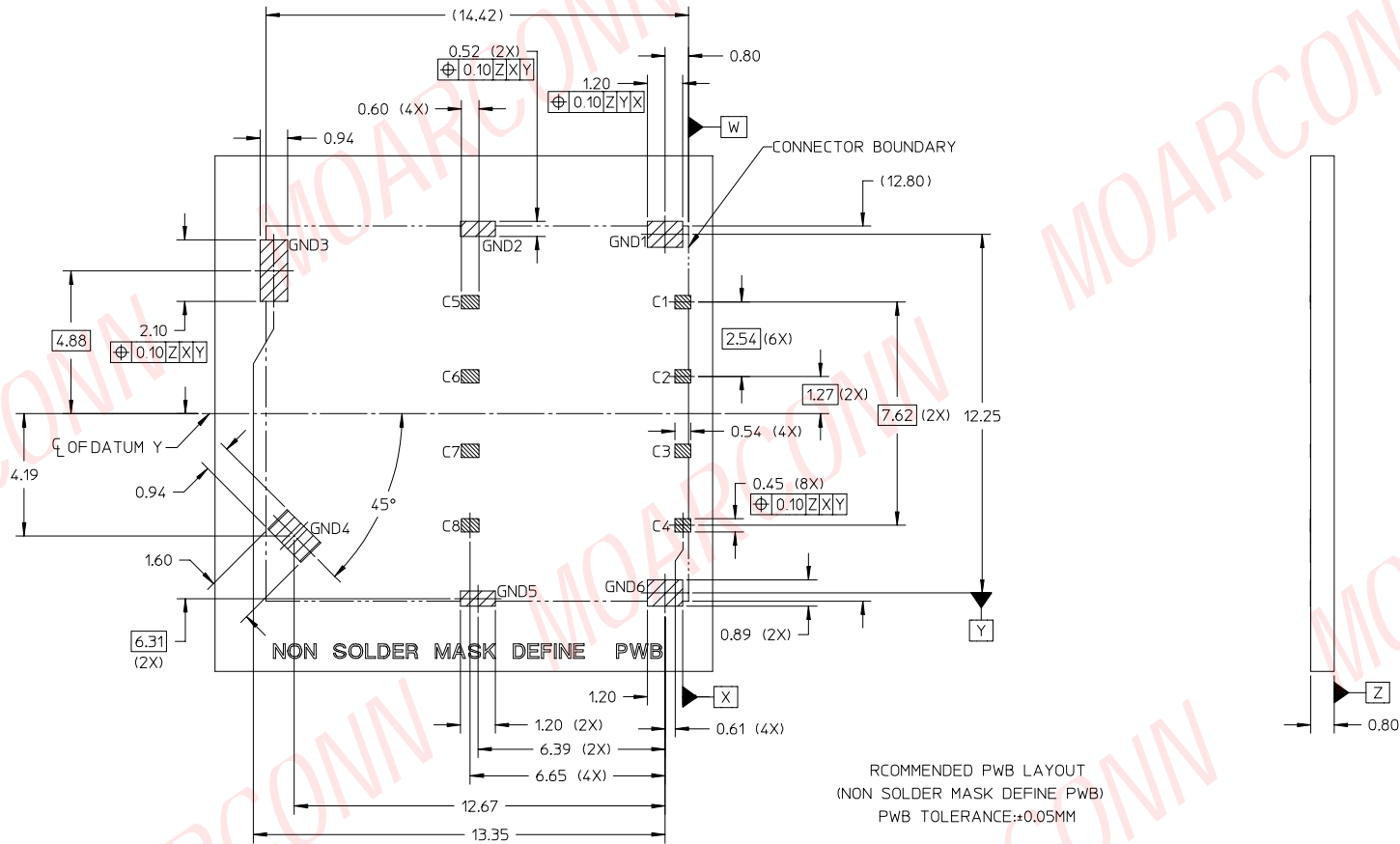
- MATERIAL: HOUSING : LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94-V0, COLOR: BLACK
TERMINAL : COPPER ALLOY
METAL SHELL : STAINLESS STEEL
- FINISH:
TERMINAL:-
CONTACT : 0.38μM MIN. GOLD OVER 1.27μM NICKEL UNDERPLATE.
SOLDERTAIL: 1.27μM MIN. MATTE TIN OVER 1.27μM NICKEL UNDERPLATE.
SHELL :-
SOLDERTAB : 1.27μM MIN. MATTE TIN OVER 1.27μM NICKEL UNDERPLATE.
- OVERALL (SOLDERTAIL & SOLDERTAB) COPLANARITY 0.08MM, MAX.
- PRODUCT SPECIFICATION: PS-78723-001
- PACKAGING SPECIFICATION: PK-78723-001
- COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV DIRECTIVE 2000/53/EC.

MOARCONN® More Connections Smart Future		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
		PRODUCT NAME : Micro SIM Card H1.35	DRAWING: Zhangli	DATE: 2025.1.4	
DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE		PRODUCT NO. : MS135-T5250-01-W	CHECK: /	DATE: /	
DIMENSION TOLERANCE X.X: ± 0.10 X.XX: ± 0.05 X.XXX: ± 0.02 ANGULAR: ± 1°		DRAWING NO. : D-MS135-T5250-01-W	APPROVED:		DATE:
REVISION NO. ECR NO. DESCRIPTION MARK DATE		SCALE: 1:1	DWG ID: P D	REV.: X0	PAGE: 1 OF 2

X0	-----	NEW RELEASE	Zhangli	2025.1.4
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1		2	3	4



All materials, plating and process meet HF requirements.



RCOMMENDED PWB LAYOUT
(NON SOLDER MASK DEFINE PWB)
PWB TOLERANCE:±0.05MM

MOARCONN® More Connections Smart Future		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
		PRODUCT NAME : Micro SIM Card H1.35		DRAWING: Zhangli	DATE: 2025.1.4
DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE		PRODUCT NO. : MS135-T5250-01-W		CHECK: /	DATE: /
DIMENSION TOLERANCE X.X: ± 0.10 X.XX: ± 0.05 X.XXX: ± 0.02 ANGULAR: ± 1°		DRAWING NO. : D-MS135-T5250-01-W		APPROVED: DATE:	
REVISION NO. ECR NO. DESCRIPTION MARK DATE		SCALE: 1:1	DWG ID: P D	REV.: X0	PAGE: 2 OF 2

X0	-----	NEW RELEASE	Zhangli	2025.1.4
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE